## **PATENT**

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re a	application of Biggs et al	)	Examiner:
Serial No.: To be assigned			Art Unit:
Filed:	Herewith	)	
For:	METHOD OF FORMING A BOND PAD ON AN I/C CHIP AND RESULTING STRUCTURE	) ) )	
Docke	et No. END920030018US1 (IEN-10-5765)		

## **INFORMATION DISCLOSURE STATEMENT**

Mail Stop Patent Application Commissioner for Patents P.O Box 1450 Alexandria, VA 22313-1450

Dear Sir:

This Information Disclosure Statement is being filed to fulfill the duty of candor and good faith toward the Patent and Trademark Office, as required pursuant to 37 C.F.R. § 1.56.

Listed on the attached PTO form 1449 is information known to persons substantively involved in the preparation of the application identified above, and that a reasonable Examiner would consider important when deciding whether to allow the application. This document is not to be construed as a representation that a search to locate the most relevant information has been made, nor a representation that more pertinent information does not exist.

Copies of the information listed on the attached PTO Form 1449 are provided herewith.

The identification of any information herein is not intended to be, and should not be understood as being, an admission that such information, in fact, constitutes "prior art" within the meaning of applicable law. The "prior art" status of any information is a matter to be resolved during prosecution.

This Information Disclosure Statement is being filed the application. Accordingly, it is not believed that any fee is required relating to the filing of this Information Disclosure Statement. If this is not the case, the Patent Office is hereby authorized to charge any related fee to Deposit Account No. 09-0457.

Respectfully submitted,

Date: 8 - 19 - 03

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enclosures

Subst. Form PTO-1449  APPLICANT'S INFORMATION DISCLOSURE STATEMENT		Atty. Docket No.: END920030018US1 (IEN-10-5765)			Serial No.: To be assigned		
			Applicant: Big	gs et al	<u> </u>		
			Filing Date: Herewith			Group:	
			U	.S. PATENT DOCUMENTS			
Initial*		Document No.	Date	Name	Class	Subcl.	Filing Date
	AA	5,885,891	03/23/99	Miyata et al	438	612	07/16/97
	AB	6,077,766	06/20/00	Sebesta et al	438	618	06/25/99
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	AD	6,387,793 B1	05/14/02	Yap et al	438	612	03/09/00
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	AP						
	AQ						
	AR					- · · · · · · · · · · · · · · · · · · ·	
	AS						

Date Considered:

ΑT

Examiner:

<sup>\*</sup>EXAMINER: Initial if reference considered, whether or not citation is in conformation with MPEP 609; draw line through citation if in conformance and not considered. Include copy of this form with next communication to applicant.